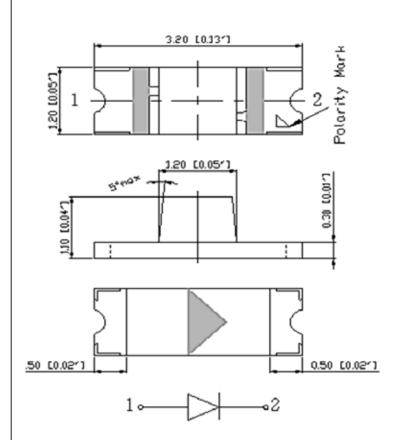
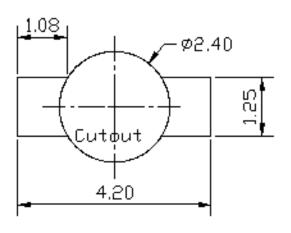


SPECIFICATION CS124AGT2C-R

PACKAGE OUTLINES



RECOMMENDED SOLDER PAD



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CS124AGT2C-R	InGaN	Green	Water Clear	140°	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	111	mW	
Operating Temperature Range	Тор	-40~+85	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

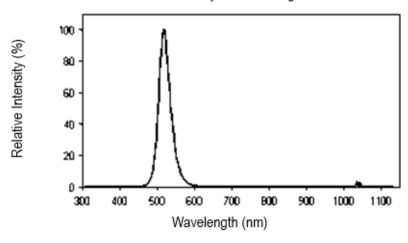
Parameter	Symbol	Toot Condition	Value			Llmit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	250	450	-	mcd
Forward Voltage	VF	IF = 20mA	-	3.2	3.7	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	140	-	Deg
Peak Wavelength	λР	IF = 20mA	-	520	-	nm
Dominant Wavelength	λD	IF = 20mA	520	525	530	nm

^{*}Tolerance of viewing angle: -10 / +5 deg.

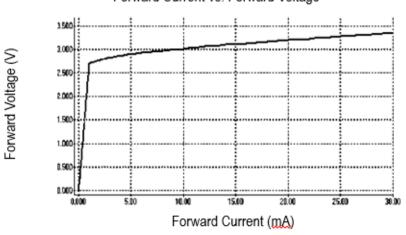


OPTICAL CHARACTERISTIC CURVES

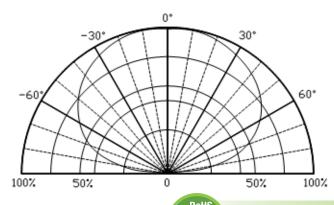
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

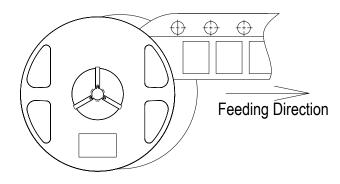




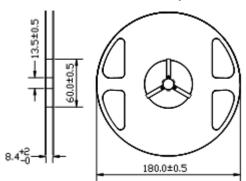
PACKAGING SPECIFICATION

PACKAGING SPECIFICATIONS

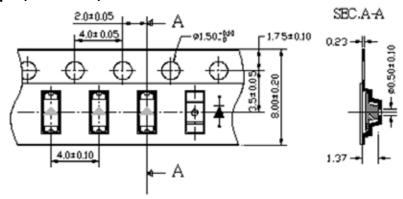
Feeding Direction



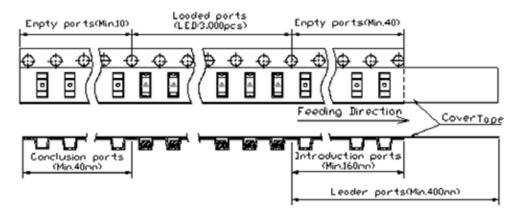
Dimensions of Reel (Unit: mm)



Dimensions of Tape (Unit: mm)



Arrangement of Tape



Notes:

- 1. Empty component pockets are sealed with top cover tape
- 2. Maximum number of missing lamp is two
- 3. Cathode is oriented towards the tape sprocket hole
- 4. 3,000 pcs/Reel

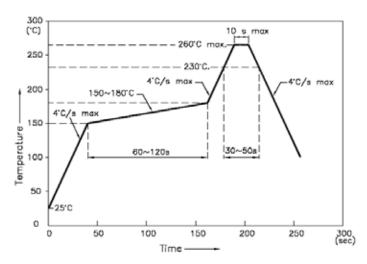




SOLDERING CONDITIONS

SOLDERING PROFILE

Reflow Temp/Time



- We recommend the reflow temperature 245°C (±5 °C) & the maximum soldering temperature should be limited to 260 °C.
- Do not cause stress to the epoxy resin while it is exposed to high temperature.
- Number of reflow process should be 2 times or less.
- Soldering Iron:
 - Basic spec is ≤ 5 sec when 260 °C. If the temperature is higher, time should be shorter (+10 °C → -1 sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230 °C.
- Rework:
 - Customer must finish rework within 5 sec under 260 °C
 - The head of iron cannot touch copper foil
 - Twin-head type is preferred

